

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6094351

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HYUNG SEOP SHIN	04/23/2020
KYUNG OH BAE	04/23/2020
RECEIVING PARTY DATA	
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Property Type	Number
Application Number:	16789859
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NAME OF SUBMITTER:	HEUNGSOO CHOI
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DATE SIGNED:	05/06/2020
Total Attachments: 2	
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COMBINED DECLARATION & ASSIGNMENT (37 CFR 1.63(e))*Application Data Sheet filed previously or concurrently*

Docket No.: NAM011.001C1

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Title: SMALL-PUNCH TEST APPARATUS FOR QUANTITATIVELY EVALUATING MATERIAL EMBRITTLEMENT BEHAVIOR UNDER VARIOUS GASEOUS HYDROGEN ENVIRONMENTS

Inventor(s): Hyung Seop SHIN; Kyung Oh BAE

Declaration

As the below-named inventor, I hereby declare that:

1. This Declaration is directed to:

The attached application, where "attached" means filed concurrently with, or
U.S. Patent Application No. 16/789,859, filed on February 13, 2020

2. The above-identified application was made or authorized to be made by me.
3. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.
4. I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Assignment from Inventor

WHEREAS, the below-named inventor (hereinafter "ASSIGNOR") invented certain new and useful improvements, technology, inventions, developments, ideas or discoveries disclosed in the above-identified application (hereinafter the "Application").

AND WHEREAS, **ANDONG NATIONAL UNIVERSITY INDUSTRY-ACADEMIC COOPERATION FOUNDATION**, with its principal place of business at 1375, Gyeongdong-ro, Andong-si Gyeongsangbuk-do, 36729, Republic of Korea (hereinafter the "ASSIGNEE"), desires to acquire the entire right, title, and interest in and to the Application.

NOW, THEREFORE, for good and valuable consideration of which receipt is hereby acknowledged, ASSIGNOR hereby acknowledges that ASSIGNOR has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest in the Application and related application(s) filed or issued upon the Application (collectively "Patent Properties"), where "Patent Properties" include, but are not limited to:

- the Application;
- all provisional application(s) to which the Application claims priority;
- all nonprovisional applications claiming priority to aforementioned provisional(s) and/or the Application, including, all divisional applications, continuation applications, and continuations-in-part applications, and reissue applications; and
- all Letters Patent of the United States which may be granted on the Application and the aforementioned nonprovisional applications, and all reissues and extensions thereof.

ASSIGNOR hereby acknowledges the ASSIGNEE as the Applicant for all aforementioned Patent Properties, and authorizes and requests the Commissioner of Patents of the United States to issue all related Letters Patent to the ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

ASSIGNOR does hereby sell, assign, transfer, and convey to ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of this assignment to ASSIGNEE, or may

COMBINED DECLARATION & ASSIGNMENT (37 CFR 1.63(e))

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Cocket No.: NAM011.001C1

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accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of all Patent Properties;

AND ASSIGNOR DOES HEREBY covenant and agree that ASSIGNOR will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to ASSIGNOR respecting the Patent Properties, and testify in any legal proceeding, assist in the preparation of any applications relating to the Patent Properties, sign/execute all lawful papers, execute and make all rightful oaths and/or declarations in connection with the Patent Properties and generally do everything possible to aid the ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for the Patent Properties.

Authorization to Add Application Information

In case this document is signed without the filing date and/or the application number in the Declaration section, I authorize the registrants of Knobbe, Martens, Olson & Bear, LLP, Customer No. 20,955 to add the filing date and application number in the blanks in the Declaration section before filing this document with the United States Patent and Trademark Office.

Legal Name of inventor 1: Hyung Seop SHIN

Signature: _____

Hyung Seop Shin

Date: _____

April 23, 2020

Legal Name of inventor 2: Kyung Oh BAE

Signature: _____

Kyung Oh BAE

Date: _____

April 23, 2020

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RECORDED: 05/06/2020

REEL: 052589 FRAME: 0341